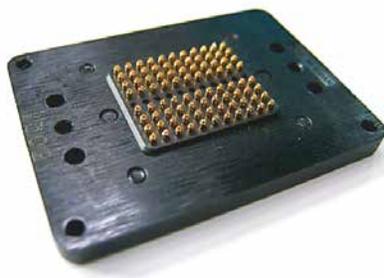


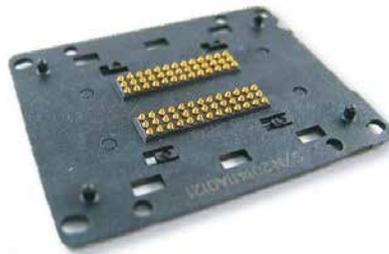
Memory Test Solutions

Memory ICs are a core component of nearly every electronic device. Memory ICs are usually categorized in volatile and non-volatile memory where volatile memory keeps its stored information when the power cycle is interrupted and volatile memory needs a constant power supply to retain its data. Most memory modules have a standardized format that can be tested with standardized test-pins. C.C.P. offers testing solutions for all common formats (DDR, Flash, eMCP, etc.) as well as customized testing solutions for your individual needs.

Design Concepts



DDR2/3 Socket



DDR3/4 Socket



eMCP Socket

Housing	Material
Injection molding	PES

Housing	Spec.
Min. Pitch	0.4mm



Manual DDR2/3 Testing Module
Single Side



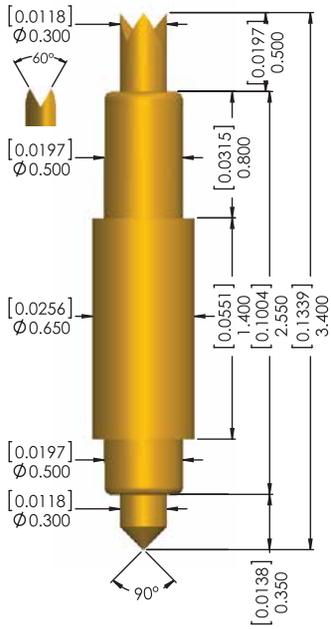
Manual DDR3 Testing Module
Double Side

Manual DDR2/3 Testing Module	Spec.
Max. Site Amount	8~16 (Single side/ Double side)
Transmission Rate (MT/s)	200MHz~1866MHz

Probe Specifications

Unit:mm; []:in

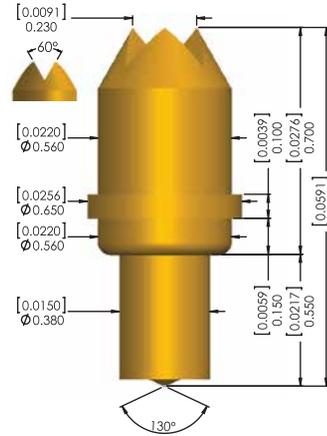
DE2-050EF25-120 DDR 2/3



Material
 Top Plunger
 BeCu, Au plated
 Barrel
 Brass, Au plated
 Spring
 SUS, Au plated
 Bottom Plunger
 BeCu, Au plated

Mechanical Spec.
 Recommended Travel
 0.40mm
 Full Travel
 0.60mm
 Spring Force
 35g±20%@0.40mm
 Operating Temp.
 -55°C~150°C

DE4-056EF09-03F0 DDR3



Material
 Top Plunger
 BeCu, Au plated
 Barrel
 SUS, Au plated
 Spring
 BeCu, Au plated
 Bottom Plunger
 BeCu, Au plated

Mechanical Spec.
 Recommended Travel
 0.40mm
 Full Travel
 0.50mm
 Spring Force
 30g±20%@0.40mm
 Operating Temp.
 -55°C~150°C

Electrical Spec. GSG

Pitch: 0.8mm Socket Material: Peek 1000

Current Rating 1A continuous
 Contact Resistance <175mΩ(AVG)
 Characteristic Impedance 37Ω
 Insertion Loss -1dB@18.6GHz
 Return Loss -20dB@2.69GHz
 Time Delay 20.4 psec
 Loop Inductance 0.76 nH
 Capacitance 0.55 pF

Electrical Spec. GSG

Pitch: 0.8mm Socket Material: Peek 1000

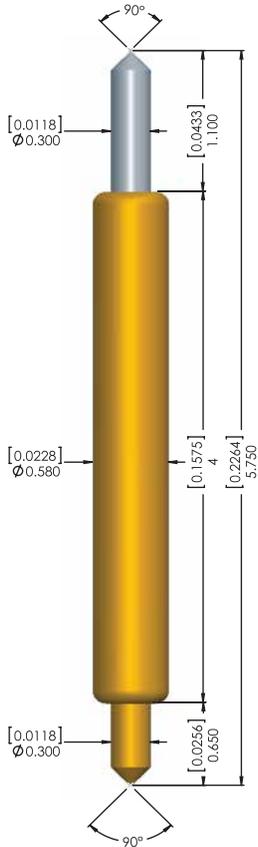
Current Rating 1A continuous
 Contact Resistance <75mΩ(AVG)
 Characteristic Impedance 36.16Ω
 Insertion Loss -1dB>20GHz
 Return Loss -20dB@5.11GHz
 Time Delay 9.4 psec
 Loop Inductance 0.34nH
 Capacitance 0.26pF

Probe Specifications

Unit:mm; []in

PE1-058EE40-01A0

Flash



Material

Top Plunger
Pd alloy

Barrel
PhBz, Au plated

Spring
SUS, Au plated

Bottom Plunger
BeCu, Au plated

Mechanical Spec.

Recommended Travel
0.80mm

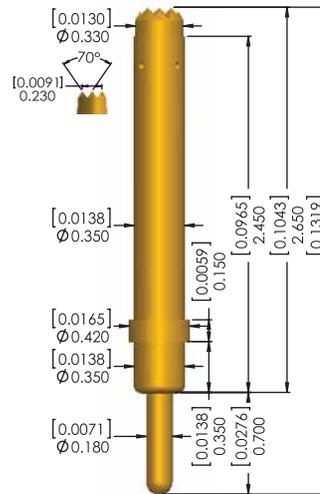
Full Travel
1.1mm

Spring Force
28g±20%@0.80mm

Operating Temp.
-55°C~150°C

DE4-035DH24-01A0

eMCP



Material

Top Plunger
BeCu, Au plated

Barrel
PhBz, Au plated

Spring
SWP, Au plated

Bottom Plunger
BeCu, Au plated

Mechanical Spec.

Recommended Travel
0.50mm

Full Travel
0.70mm

Spring Force
27g±20%@0.50mm

Operating Temp.
-15°C~125°C

Electrical Spec.

Pitch: 0.8mm Socket Material: Peek 1000



Current Rating 1A continuous

Contact Resistance <75mΩ(AVG)

Characteristic Impedance 41.2Ω

Insertion Loss -1dB>20GHz

Return Loss -20dB@2.56GHz

Time Delay 32.2 psec

Loop Inductance 1.33nH

Capacitance 0.78pF

Electrical Spec.

Pitch: 0.5mm Socket Material: Peek 1000



Current Rating 1A continuous

Contact Resistance <75mΩ(AVG)

Characteristic Impedance 40.06Ω

Insertion Loss -1dB>20GHz

Return Loss -20dB@4.5GHz

Time Delay 17.22 psec

Loop Inductance 0.69 nH

Capacitance 0.43 pF